

## PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Xiaoyong Deng</td> <td>12/08/2011</td> </tr> <tr> <td>Yutian Wang</td> <td>12/08/2011</td> </tr> <tr> <td>test test</td> <td>01/28/2010</td> </tr> </tbody> </table>		Name	Execution Date	Xiaoyong Deng	12/08/2011	Yutian Wang	12/08/2011	test test	01/28/2010
Name	Execution Date								
Xiaoyong Deng	12/08/2011								
Yutian Wang	12/08/2011								
test test	01/28/2010								
RECEIVING PARTY DATA									
Name:	Hangzhou H3C Technologies Co., Ltd.								
Street Address:	Huawei Hangzhou Manufacturing Base, 310 Liuhe Road, Zhijiang Hi-Tech Park, Hi-Tech Industry Development Zone, Hangzhou								
City:	Zhejiang								
State/Country:	CHINA								
Postal Code:	310053								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13384822</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13384822				
Property Type	Number								
Application Number:	13384822								
CORRESPONDENCE DATA									
Fax Number:	(970)778-4063								
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Total Attachments: 1 source=82897162-Assignment#page1.tif									

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PATENT

HEPPELLETT-PACKARD COMPANY  
Intellectual Property Administrator  
3404 E. Harmony Blvd  
Mail Stop 35  
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 82897162

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each) have agreed and hereby agree to assign to Hangzhou H3C Technologies Co., Ltd., a company having its principal place of business at Huawei Hangzhou Manufacturing Base, 310 Liuh Road, Zhejiang Hi-Tech Park, Hangzhou Hi-Tech Industry Development Zone, Hangzhou, Zhejiang 310053, the People's Republic of China, (hereinafter H3C), in furtherance of my/our obligations to H3C and its subsidiaries and affiliates, and do hereby assign and transfer to H3C, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

Apparatus And Method For Recording Reboot Reason Of Equipment

Filing Date: Jan 19, 2012

Application No.: 13/384,822

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-IP's), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore, and any reissues, or reexaminations, or extensions of said Letters Patent.

I/we additionally authorize H3C to file applications in my/our name for Letters Patent in any country, to be held and enjoyed by H3C, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, renewed or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made.

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent, to H3C, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to H3C, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-IP's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid H3C, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by H3C.

AND I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to H3C, as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the serial number and filing date of said application now identified by the Record ID and title set forth above as soon as the same shall have been made known to them by the United States Patent and Trademark Office.

Xiaoyong Deng  
Inventor's Signature

2011.12.08  
Date Assignment Signed

Xiaoyong Deng  
Inventor's Typed Name

Date Application Signed

Yuetian Wang  
Inventor's Signature

2011.12.08  
Date Assignment Signed

Yuetian Wang  
Inventor's Typed Name

Date Application Signed